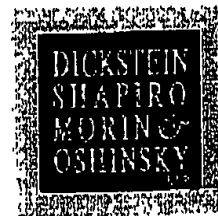


FAX TRANSMISSION



DATE: December 4, 2001
CLIENT NO.: M4065.0184
MESSAGE TO: Examiner Chuong A. Luu
COMPANY: U.S. Patent and Trademark Office, Art Unit 2825
FAX NUMBER: 703-308-7722
PHONE: 703-305-0129
FROM: Mark J. Thronson
PHONE: (202) 775-4742

FAX COPY RECEIVED

DEC 3 - 2001

TECHNOLOGY CENTER 2800

PAGES (Including Cover Sheet):

5

HARD COPY TO FOLLOW:

☐ YES

☒ NO

Please file the attached Amendment in U.S. Patent Application No. 09/594,510. Please charge any deficiencies in the fees to Deposit Account No. 04-1073.

Applicants' undersigned representative hereby certifies, pursuant to 37 C.F.R. § 1.8, that the attached Amendment is being transmitted by facsimile to the U.S. Patent and Trademark Office on December 4, 2001.

Mark J. Thronson, Reg. No. 33,082

FAX COPY RECEIVED

DEC 4 - 2001

TECHNOLOGY CENTER 2800

If your receipt of this transmission is in error, please notify this firm immediately by collect call to our Facsimile Department at 202-861-9106, and send the original transmission to us by return mail at the address below.

This transmission is intended for the sole use of the individual and entity to whom it is addressed, and may contain information that is privileged, confidential and exempt from disclosure under applicable law. You are hereby notified that any dissemination, distribution or duplication of this transmission by someone other than the intended addressee or its designated agent is strictly prohibited.

Docket No.: M4065.0184/P184
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Alan G. Wood et al.

Application No.: 09/594,510

Filed: June 16, 2000

For: SEMICONDUCTOR DEVICE PACKAGE
AND METHOD

Group Art Unit: 2825

Examiner: C. Luu

*C/A Amdb
12/7/01
A. Walli*

AMENDMENT

Box Non-Fee Amendment
Commissioner for Patents
Washington, DC 20231

FAX COPY RECEIVED

DEC 4 - 2001

TECHNOLOGY CENTER 2800

Dear Sir:

In response to the Office Action dated September 4, 2001, please amend the
above-identified U.S. Patent application as follows:

IN THE CLAIMS:

Rewrite claim 11 as follows:

9531 11. (Amended) A method of making semiconductor device packages,
comprising:
forming a layered assembly by attaching a semiconductor wafer and a stiff metal
layer to a dielectric layer;